

What is claimed is:

1. A memory module comprising:

5 a board;

a memory device attached to the board; and

10 a heat dissipation means arranged between the memory device and the board.

2. The memory module of claim 1, wherein the heat dissipation means includes a heat-conducting paste between the board 10 and the memory device (12).

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3. The memory module of claim 1, wherein the heat dissipation means includes an area of the board at which solder varnish covering the board is removed.

20 4. Memory module of claim 1, wherein the heat dissipation means includes a metal layer.

25 5. The memory module of claim 4, wherein the metal layer is connected to a supply line to which, in operation, a supply potential is applied.

6. The memory module of claim 4, wherein the metal layer includes a conductive trace.

30 7. The memory module of claim 6, wherein the conductive trace is meander-shaped.

8. The memory module of claim 4, wherein the metal layer includes a heat sink.

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9. The memory module of claim 2, wherein the heat dissipation means includes a contact hole.

10. The memory module of claim 9, wherein the contact hole is connected to a supply line at which, in operation, a supply potential is applied.

5 11. The memory module of claim 1, further comprising a frame which is arranged at the edge of the board and comprises a heat-conductive material.

10 12. The memory module of claim 11, wherein the metal frame comprises taps by means of which same can be heat-conductively connected to a socket or a motherboard.